

Product / Assembly Name:	nShield Connect XC	nShield Connect XC SCAP	nShield Connect XC Serial Console	nShield Connect CLX
Product / Assembly Model:	NH2075	NH2082	NH2089	NH3003
Marketing Number:	NH2075-x ¹	NH2082-x ¹	NH2089-x ¹	NH3003-x ¹

Note 1 - where x can be B, M or H (for Base, Mid or High variants) and 8K-ISS or 16K-ISS (for Issuance HSM variants)

Entrust uses commercially reasonable efforts to ensure compliance with RoHS regulation by our supply chain. In reliance on the responses that we have received and data that we have obtained from our suppliers as well as information obtained through our own audit program, Entrust certifies that, to the best of our knowledge and belief the above listed products are manufactured in compliance with the Restriction of Hazardous Substances (RoHS), Directive 2011/65/EU as modified by 2015/863/EU and does not contain any of the hazardous substances listed in the table below in concentrations above the legal limits defined.

Where a specific application is exempted from restriction, a valid and current exemption may have been used to demonstrate compliance (as defined in annex III of 2011/65/EU; see the next page for details).

Maximum concentration values tolerated by weight in homogeneous materials:

(Excluding materials and parts covered by a valid and current RoHS exemption)

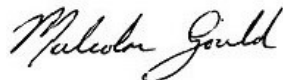
Lead (0,1%)	Polybrominated diphenyl ethers (PBDE) (0,1%)	Cadmium (0,01%)	Hexavalent chromium (0,1 %)	Polybrominated biphenyls (PBB) (0,1 %)
Mercury (0,1%)	Bis (2-ethylhexyl) phthalate (DEHP) (0.1%)	Butyl benzyl phthalate (BBP) (0.1%)	Dibutyl phthalate (DBP) (0.1 %)	Diisobutyl phthalate (DIBP) (0.1 %)

Declaration for and on behalf of nCipher Security

an Entrust company

Name: *Malcolm Gould*

Signature & Date:



1st March 2024

Position:

Regulatory Compliance Officer

This declaration is based in part on information provided to nCipher by its suppliers. The RoHS Directive restricts the use of certain substances in electronic products; including certain allowable exemptions as defined in Annex III of 2011/65/EU.

- Item(s) does not contain RoHS restricted substances per the definition above
- Item(s) contains RoHS restricted substances above the limits per the definition above, except for lead in solder and selected exemptions, if any
- Item(s) does not contain RoHS restricted substances per the definition above, except for selected exemptions
- Item(s) is obsolete, no information is available
- Item(s) is unknown, no information is available

Exemption List from Directive 2011/65/EU Annex III - Consolidated version of 2019

- 6(a)-I Lead as an alloying element in steel for machining purposes containing up to 0,35 % lead by weight and in batch hot dip galvanised steel components containing up to 0,2 % lead by weight.
- 6(b)-I Lead as an alloying element in aluminium containing up to 0,4 % lead by weight, provided it stems from lead-bearing aluminium scrap recycling.
- 6(b)-II Lead as an alloying element in aluminium for machining purposes with a lead content up to 0,4 % by weight.
- 6(c) Copper alloy containing up to 4% lead by weight.
- 7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).
- 7(c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.
- 7(c)-II Lead in dielectric ceramic in capacitors for a voltage of 125 V AC or 250 V DC or higher.
- 8(b)-I Cadmium and its compounds in electrical contacts used in: – circuit breakers; – thermal sensing controls; – thermal motor protectors (excluding hermetic thermal motor protectors); – AC switches rated at: • 6 A and more at 250 V AC and more; or • 12 A and more at 125 V AC and more; – DC switches rated at 20 A and more at 18 V DC and more; and – switches for use at voltage supply frequency \geq 200 Hz.
- 13(a) Lead in white glasses used for optical applications.
- 13(b)-I Lead in ion coloured optical filter glass types.
- 13(b)-II Cadmium in striking optical filter glass types; excluding applications falling under point 39 of this Annex (Annex III).
- 13(b)-III Cadmium and lead in glazes used for reflectance standards.
- 15(a) Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies: – a semiconductor technology node of 90nm or larger; – a single die of 300 mm² or larger in any semiconductor technology node; – stacked die packages with die of 300 mm² or larger, or silicon interposers of 300 mm² or larger.



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